

# MBM 1200E17D

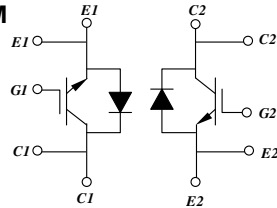
PRELIMINARY SPECIFICATION

Silicon N-channel IGBT

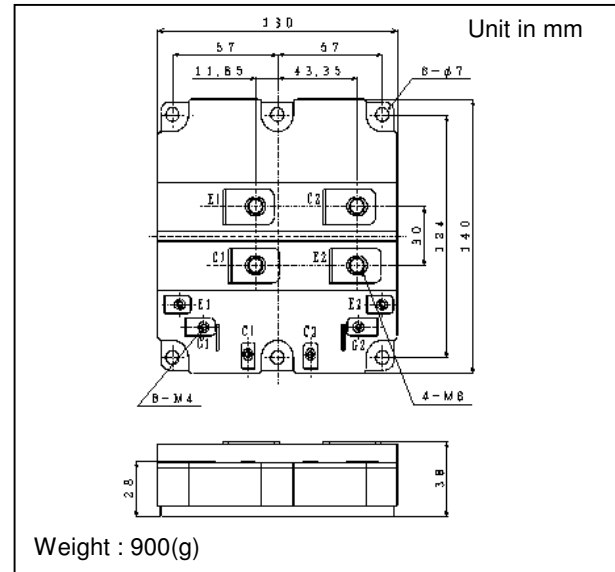
## 1. FEATURES

- \* High speed, low loss IGBT module.
- \* Low driving power due to low input capacitance MOS gate.
- \* Low noise due to ultra soft fast recovery diode.
- \* High reliability, high durability module.
- \* High thermal fatigue durability (Al-SiC base plate.)  
( $\Delta T_c=70^\circ\text{C}$ ,  $N>30,000$ cycles)

## CIRCUIT DIAGRAM



## OUTLINE DRAWING



## 3. ABSOLUTE MAXIMUM RATINGS ( $T_c=25^\circ\text{C}$ )

Item	Symbol	Unit	MBM 1200E17D
Collector Emitter Voltage	$V_{CES}$	V	1,700
Gate Emitter Voltage	$V_{GES}$	V	$\pm 20$
Collector Current	DC	$I_C$	1,200
	1ms	$I_{Cp}$	2,400
Forward Current	DC	$I_F$	1,200
	1ms	$I_{FM}$	2,400
Junction Temperature	$T_j$	$^\circ\text{C}$	-40 ~ +125
Storage Temperature	$T_{stg}$	$^\circ\text{C}$	-40 ~ +125
Isolation Voltage	$V_{ISO}$	$V_{RMS}$	4,000 (AC 50Hz, 1 minute)
Screw Torque	Terminals (M4)	-	2 (1)
	Terminals (M8)	-	15 (2)
	Mounting (M6)	-	6 (3)

Notes: Recommended Value (1)  $1.8 \pm 0.2 \text{ N}\cdot\text{m}$ , (2)  $15^{+0}_{-3} \text{ N}\cdot\text{m}$ , (3)  $5.5 \pm 0.5 \text{ N}\cdot\text{m}$

## 4. ELECTRICAL CHARACTERISTICS

Item	Symbol	Unit	Min.	Typ.	Max.	Test Conditions	
Collector Emitter Cut-Off Current	$I_{CES}$	mA	-	-	5.0	$V_{CE}=1,700\text{V}$ , $V_{GE}=0\text{V}$ , $T_j=25^\circ\text{C}$	
			-	5	17	$V_{CE}=1,700\text{V}$ , $V_{GE}=0\text{V}$ , $T_j=125^\circ\text{C}$	
Gate Emitter Leakage Current	$I_{GES}$	nA	-500	-	+500	$V_{GE}=\pm 20\text{V}$ , $V_{CE}=0\text{V}$ , $T_j=25^\circ\text{C}$	
Collector Emitter Saturation Voltage	$V_{CE(sat)}$	V	-	2.7	3.3	$I_C=1200\text{A}$ , $V_{GE}=15\text{V}$ , $T_j=125^\circ\text{C}$	
Gate Emitter Threshold Voltage	$V_{GE(TO)}$	V	5.0	6.5	8.0	$V_{CE}=10\text{V}$ , $I_C=120\text{mA}$ , $T_j=25^\circ\text{C}$	
Input Capacitance	$C_{ies}$	nF	-	110	-	$V_{CE}=10\text{V}$ , $V_{GE}=0\text{V}$ , $f=100\text{kHz}$ , $T_j=25^\circ\text{C}$	
Internal Gate Resistance	$R_{g(int)}$	$\Omega$	-	1.3	-		
Switching Times	Rise Time	$t_r$	-	0.5	1.0	$V_{CC}=900\text{V}$ , $I_C=1200\text{A}$ $L=100\text{nH}$ , $C_{GE}=120\text{nF(TBD)}$ (4) $R_G=1.5\Omega(\text{TBD})$ (4) $V_{GE}=\pm 15\text{V}$ , $T_j=125^\circ\text{C}$	
	Turn On Time	$t_{on}$	-	0.9	1.8		
	Fall Time	$t_f$	-	0.3	0.6		
	Turn Off Time	$t_{off}$	-	1.6	3.2		
Peak Forward Voltage Drop	$V_{FM}$	V	-	1.9	2.3	$I_C=1200\text{A}$ , $V_{GE}=0\text{V}$ , $T_j=125^\circ\text{C}$	
Reverse Recovery Time	$t_{rr}$	$\mu\text{s}$	-	0.5	1.0	$V_{CC}=900\text{V}$ , $I_C=1200\text{A}$ ,	
Turn On Loss	$E_{on(10\%)}$	J/P	-	0.13	1.7	$L=100\text{nH}$ , $C_{GE}=120\text{nF(TBD)}$ (4)	
Turn Off Loss	$E_{off(10\%)}$	J/P	-	0.43	0.56	$R_G=1.5\Omega(\text{TBD})$ (4)	
Reverse Recovery Loss	$E_{rr(10\%)}$	J/P	-	0.35	0.46	$V_{GE}=\pm 15\text{V}$ , $T_j=125^\circ\text{C}$	
Thermal Resistance	IGBT	$R_{th(j-c)}$	K/W	-	-	0.023	Junction to case
	FWD	$R_{th(j-c)}$	K/W	-	-	0.035	
Contact Thermal Resistance		$R_{th(c-f)}$	K/W	-	0.008	-	Case to fin

Notes:(4)  $R_G$  value is a test condition value for evaluation, not recommended value.

Please, determine the suitable  $R_G$  value by measuring switching behaviors.

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